



**ATTENTION**  
OBSERVE PRECAUTIONS  
FOR HANDLING  
ELECTROSTATIC  
DISCHARGE  
SENSITIVE  
DEVICES

Part Number: KAAF-5050RGS-13

Hyper Red  
Green  
Blue

### Features

- Chips can be controlled separately.
- Suitable for all SMT assembly and solder process.
- Available on tape and reel.
- White SMD package, silicone resin.
- Package: 500pcs / reel.
- Moisture sensitivity level : level 3.
- RoHS compliant.

### Description

The Hyper Red device is based on light emitting diode chip made from AlGaInP.

The Green source color devices are made with InGaN Light Emitting Diode.

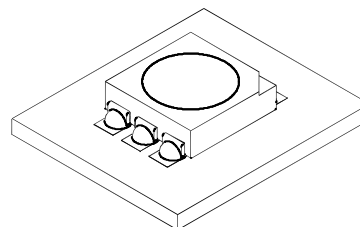
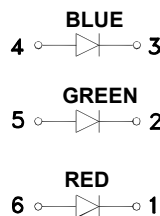
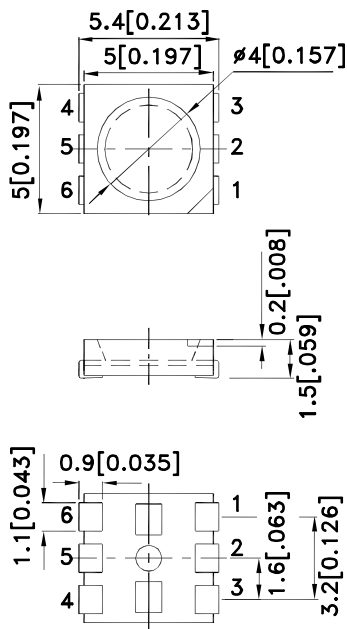
The Blue source color devices are made with InGaN Light Emitting Diode.

Static electricity and surge damage the LEDs.

It is recommended to use a wrist band or anti-electrostatic glove when handling the LEDs.

All devices, equipment and machinery must be electrically grounded.

### Package Dimensions



#### Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is  $\pm 0.2(0.008)$  unless otherwise noted.
3. The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.
4. The device has a single mounting surface. The device must be mounted according to the specifications.

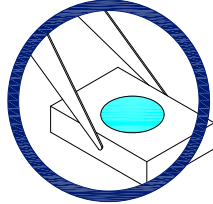


## Handling Precautions

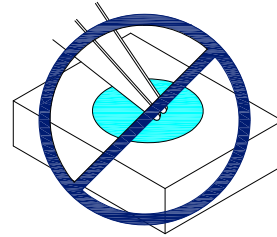
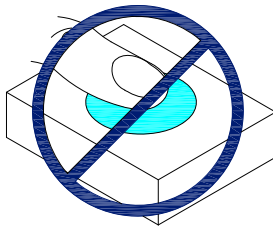
Compare to epoxy encapsulant that is hard and brittle, silicone is softer and flexible. Although its characteristic significantly reduces thermal stress, it is more susceptible to damage by external mechanical force.

As a result, special handling precautions need to be observed during assembly using silicone encapsulated LED products. Failure to comply might lead to damage and premature failure of the LED.

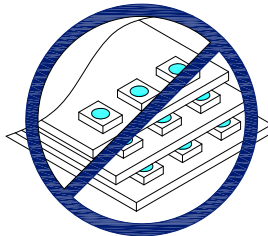
1. Handle the component along the side surfaces by using forceps or appropriate tools.



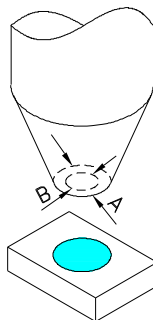
2. Do not directly touch or handle the silicone lens surface. It may damage the internal circuitry.



3. Do not stack together assembled PCBs containing exposed LEDs. Impact may scratch the silicone lens or damage the internal circuitry.



- 4.1. The inner diameter of the SMD pickup nozzle should not exceed the size of the LED to prevent air leaks.
- 4.2. A pliable material is suggested for the nozzle tip to avoid scratching or damaging the LED surface during pickup.
- 4.3. The dimensions of the component must be accurately programmed in the pick-and-place machine to insure precise pickup and avoid damage during production.



5. As silicone encapsulation is permeable to gases, some corrosive substances such as  $H_2S$  might corrode silver plating of leadframe. Special care should be taken if an LED with silicone encapsulation is to be used near such substances.

Detailed application notes are listed on our website.

[http://www.kingbright.com/application\\_notes](http://www.kingbright.com/application_notes)

## Selection Guide

Part No.	Dice	Lens Type	Iv (mcd) [2] @ 30mA		Iv (mcd) [2] @ 50mA		Viewing Angle [1]
			Min.	Typ.	Min.	Typ.	2θ1/2
KAAF-5050RGBS-13	Hyper Red (AlGaInP)	Water Clear	-	-	1000	1400	120°
	Green (InGaN)		1000	1400	-	-	
	Blue (InGaN)		300	420	-	-	

Notes:

- θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.
- Luminous Intensity / Luminous Flux: +/-15%
- Luminous intensity value is traceable to the CIE127-2007 compliant national standards.

## Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Typ.	Max.	Units	Test Conditions
$\lambda_{peak}$	Peak Wavelength	Hyper Red Green Blue	640 520 465		nm	I <sub>F</sub> =50mA I <sub>F</sub> =30mA I <sub>F</sub> =30mA
$\lambda_D$ [1]	Dominant Wavelength	Hyper Red Green Blue	625 525 470		nm	I <sub>F</sub> =50mA I <sub>F</sub> =30mA I <sub>F</sub> =30mA
$\Delta\lambda_{1/2}$	Spectral Line Half-width	Hyper Red Green Blue	25 35 22		nm	I <sub>F</sub> =50mA I <sub>F</sub> =30mA I <sub>F</sub> =30mA
C	Capacitance	Hyper Red Green Blue	27 100 100		pF	V <sub>F</sub> =0V;f=1MHz
V <sub>F</sub> [2]	Forward Voltage	Hyper Red Green Blue	2.5 3.3 3.5	3.2 4.1 4.5	V	I <sub>F</sub> =50mA I <sub>F</sub> =30mA I <sub>F</sub> =30mA
I <sub>R</sub>	Reverse Current	Hyper Red Green Blue		10 50 50	uA	V <sub>R</sub> =5V

Notes:

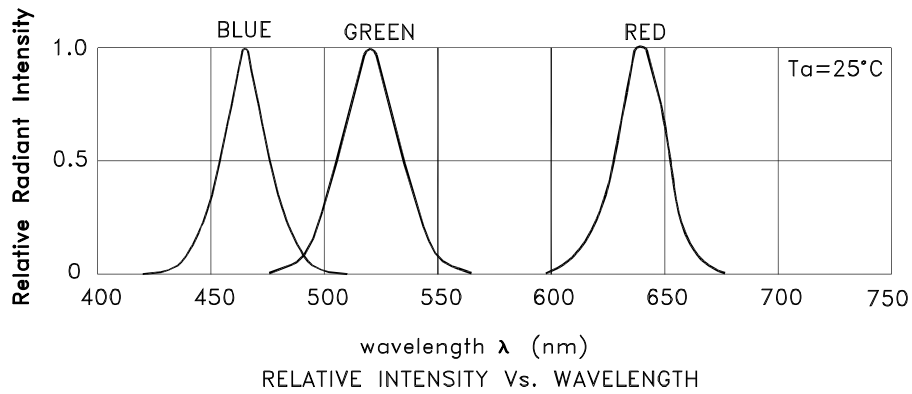
- Wavelength: +/-1nm.
- Forward Voltage: +/-0.1V.
- Wavelength value is traceable to the CIE127-2007 compliant national standards.

## Absolute Maximum Ratings at TA=25°C

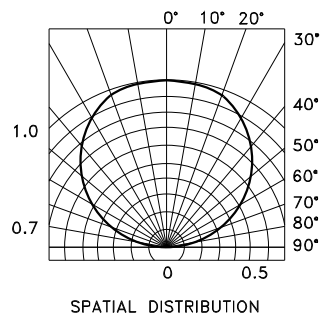
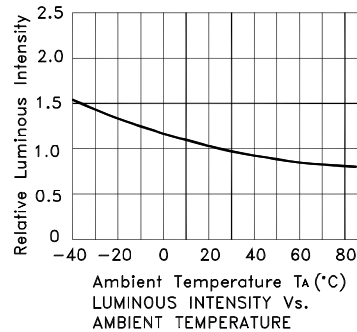
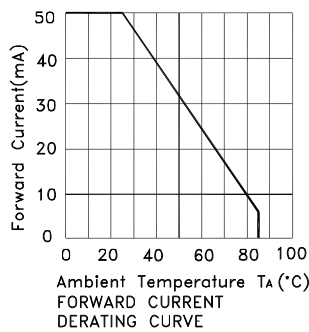
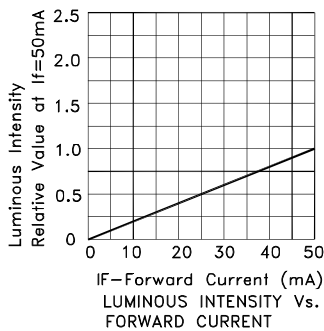
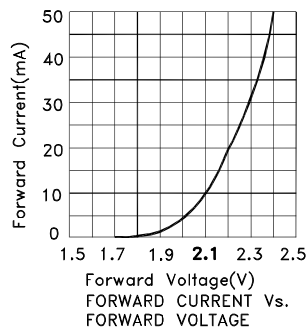
Parameter	Hyper Red	Green	Blue	Units
Power dissipation [1]	350			mW
DC Forward Current	50	30	30	mA
Peak Forward Current [2]	150	100	100	mA
Reverse Voltage	5			V
Operating Temperature	-40°C To +85°C			
Storage Temperature	-40°C To +85°C			

Notes:

- Within 350mW at all chips are lightened.
- 1/10 Duty Cycle, 0.1ms Pulse Width.

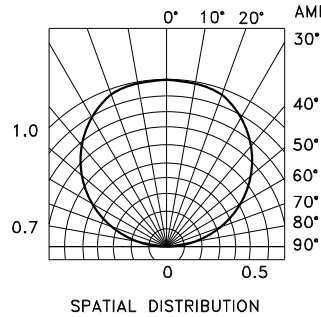
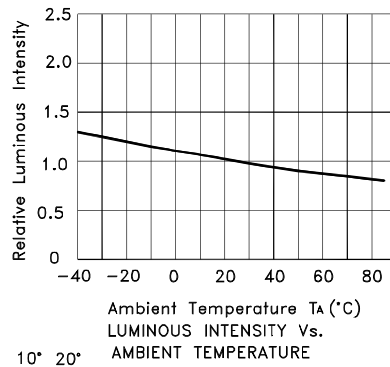
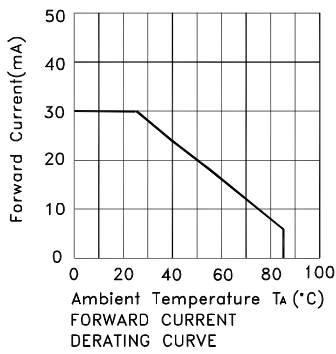
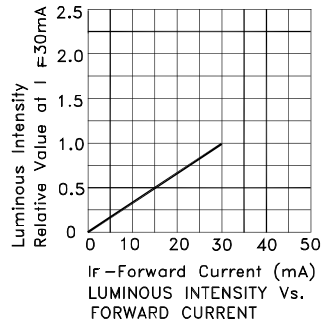
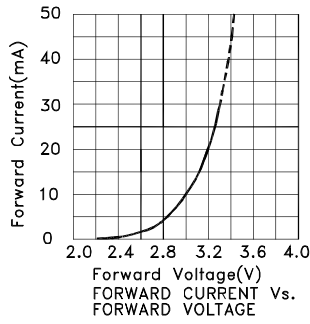


## KAAF-5050RGB-13 Hyper Red



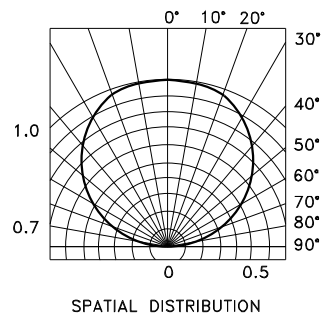
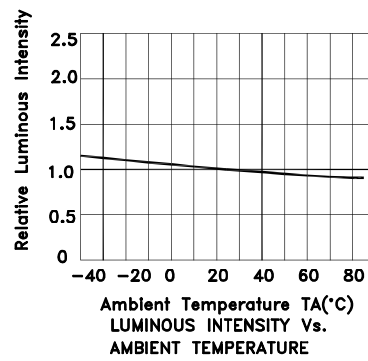
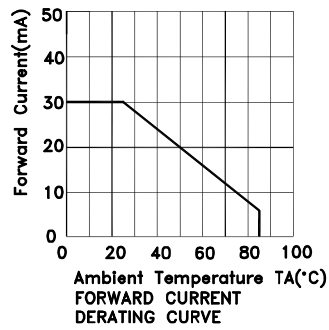
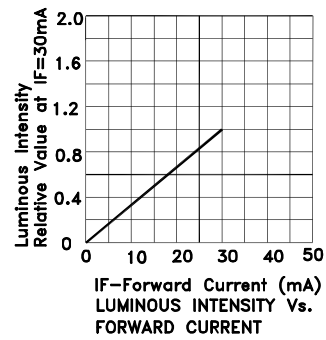
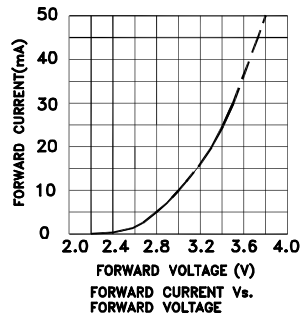
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## Green



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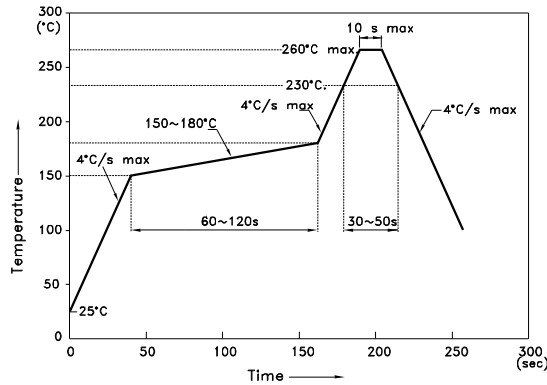
## Blue



## KAAF-5050RGS-13

Reflow soldering is recommended and the soldering profile is shown below.  
Other soldering methods are not recommended as they might cause damage to the product.

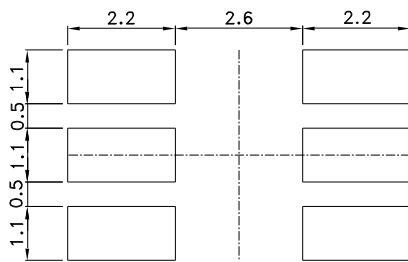
Reflow Soldering Profile For Lead-free SMT Process.



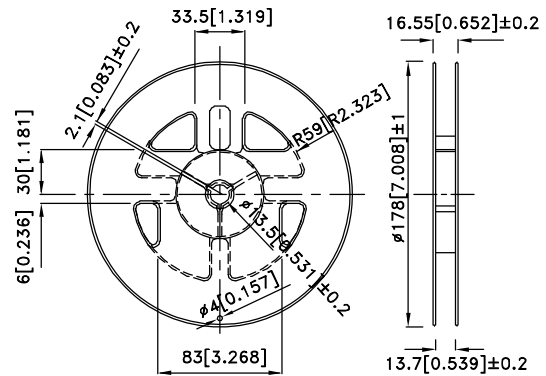
NOTES:

1. We recommend the reflow temperature 245°C(+/-5°C). The maximum soldering temperature should be limited to 260°C.
2. Don't cause stress to the epoxy resin while it is exposed to high temperature.
3. Number of reflow process shall be 2 times or less.

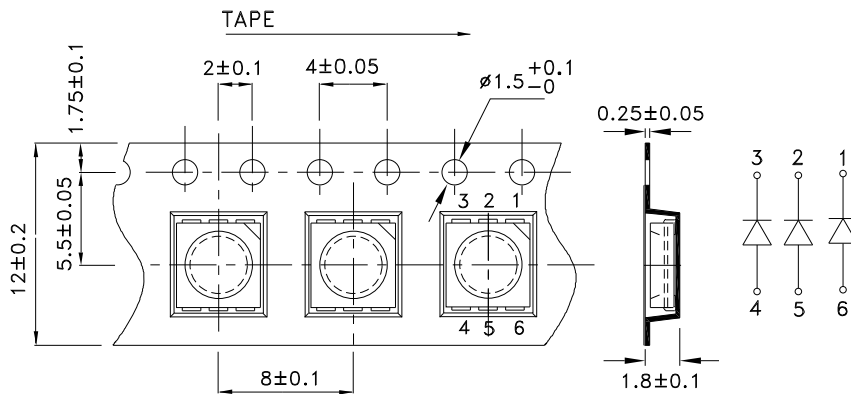
### Recommended Soldering Pattern (Units : mm; Tolerance: ± 0.1)



### Reel Dimension



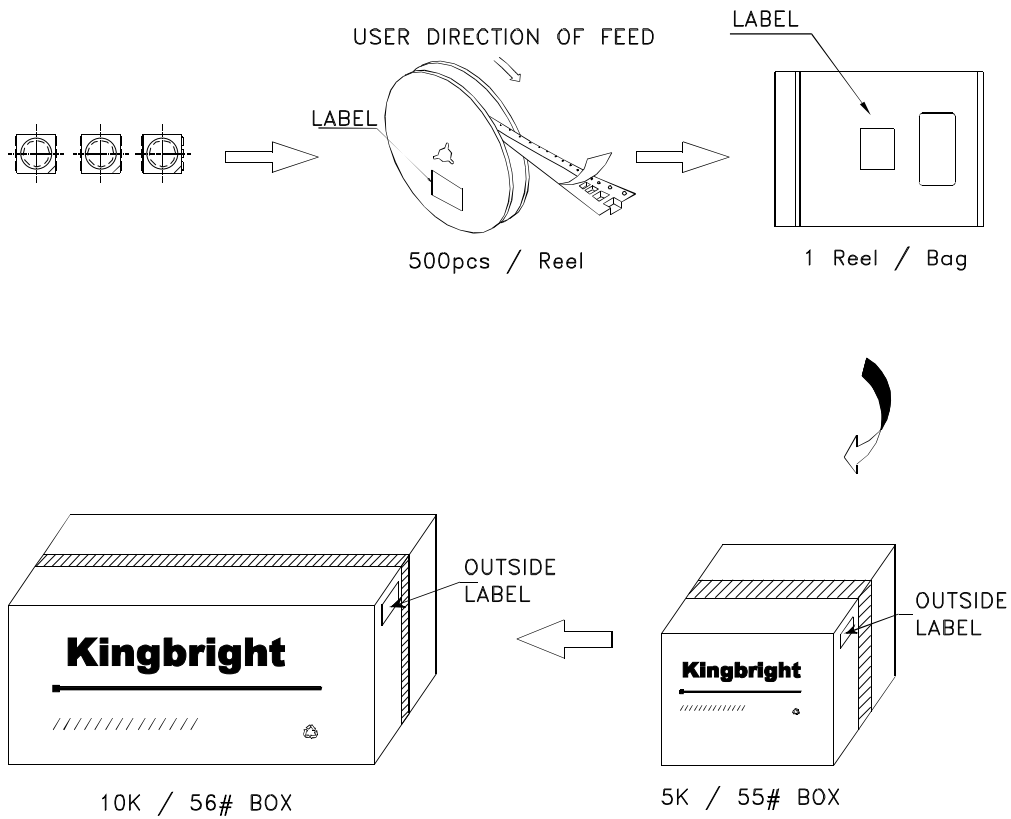
### Tape Dimensions (Units : mm)



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## PACKING & LABEL SPECIFICATIONS

## KAAF-5050RGB5-13



<b>Kingbright</b>		
P/NO: KAAF-5050xxx		
QTY: 500 pcs	Q.C.	Q C XX XX XXXX PASSED
S/N: XXXX		
CODE: XXX		
LOT NO:		
XXXXXXXXXXXXXXXXXXXX		
RoHS Compliant		